

Specification of Electret Condenser Microphone

(RoHS Compliance&Halogen-Free)

Customer Name: Customer Model:

GoerTek Model: B4013AM423-098

(GoerTek	CUSTOMER APPROVAL
DESIGN	Jery.Yang /July 4,2018	
CHECK	Anna.An /July 4,2018	
STANDARD	Sweety.Liu /July 4,2018	
APPROVAL	Near.An /July 4,2018	

Tel: +86 536 3051234 E- Mail: goertek@goertek.com Website: http://www.goertek.com

Address: No.268 Dongfang Road, High-Tech Industry Development District, Weifang, Shandong, P.R.C.



Restricted

1 Security warning

The information contained in this document is the exclusive property of GoerTek Inc. and should not be disclosed to any third party without the written consent of GoerTek Inc.

2 Publication history

Version	Date	Description	Design	Approval
1.0	2018.07.04	New Design	Jery.Yang	Near.An

3 Symbols Show

	Symbols	Show			
	O	Signify Customer's Special Characteristic.			
Signify GoerTek Special Characteristic.		Signify GoerTek Special Characteristic.			



Contents

1	Test Condition ————————————————————————————————————	- 4
2	Electrical Characteristics ————————————————————————————————————	- 4
3	Frequency Response Curve and Limits ————————————————————————————————————	- 4
4	Measurement Circuit ————————————————————————————————————	- 5
5	Test setup Drawing	- 5
6	Mechanical Characteristics	- 6
	6.1 Appearance Drawing — — — — — — — — — — — — — — — — — — —	- 6 - 6
7	Structure of SMD MIC	- 7
8	Reliability Test	- 8
	8.1 Vibration Test — 8.2 Drop Test — 8.3 Temperature Test — 8.4 Humidity Test — 8.5 Temperature Cycle Test — 8.6 Temperature Shock Test — 8.7 ESD Shock Test — 8.8 Reflow Test —	- 8 - 8 - 8 - 8 - 8
9	Package	- 9
9	9.1 Taping Specification ————————————————————————————————————	- 9 - 10 - 10
	9.1 Taping Specification	- 9 - 10 - 10 - 11
10	9.1 Taping Specification ————————————————————————————————————	- 9 - 10 - 10 - 11
10	9.1 Taping Specification	- 9 - 10 - 10 - 11 - 11
10	9.1 Taping Specification	- 9 - 10 - 10 - 11 - 11 - 12 - 12
10	9.1 Taping Specification	- 9 - 10 - 10 - 11 - 11 - 12 - 12 - 13 - 13
10 11	9.1 Taping Specification ————————————————————————————————————	- 9 - 10 - 10 - 11 - 11 - 12 - 12 - 13 - 13 - 13
10 11	9.1 Taping Specification	- 9 - 10 - 11 - 11 - 12 - 12 - 13 - 13 - 14 - 15 - 15 - 15 - 15



PRODUCT SPECIFICATIONS

Type: Electret Condenser Microphone

Model: B4013AM423-098

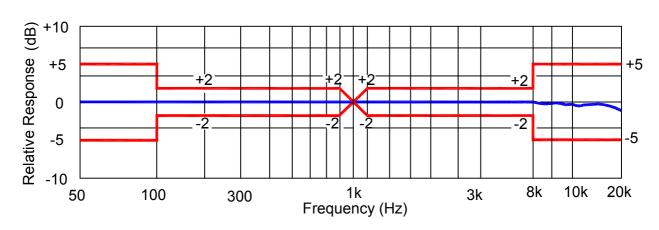
1 Test Condition (Vs=2.0V , RL=2.2k Ω , L=50cm)

Standard Conditions (Re. IEC 60268-4)	Temperature	Humidity	Air pressure	
Environment Conditions	+15℃~+35℃	25%RH~75%RH	86kPa \sim 106kPa	
Judgement Conditions	+20 ℃ ±2 ℃	60%RH~70%RH	86kPa \sim 106kPa	

2 Electrical and Acoustical Characteristics

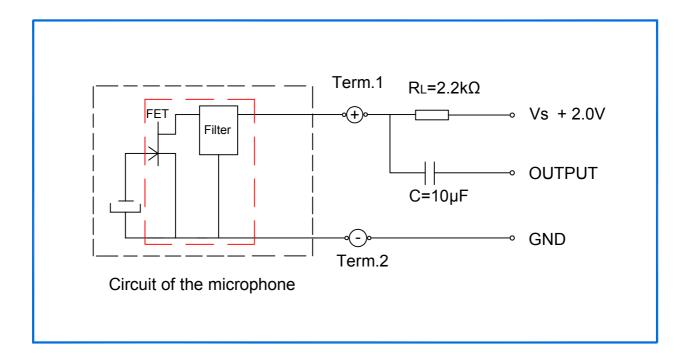
Item	Symbol	Test Conditions	Min	Тур	Max	Unit
Sensitivity	S	f=1kHz, Pin=1Pa	-45	-42	-39	dB 0dB=1V/Pa
Output Impedance	Zout	f=1kHz, Pin=1Pa			2.2k	Ω
Directivity	D(θ)	Omnidirectional				dB
Current Consumption	I				500	μA
S/N Ratio	S/N(A)	f=1kHz, Pin=1Pa A-Weighted Curve	58			dB
Decreasing Voltage Characteristic	ΔS	f=1kHz, Pin=1Pa Vs=2-1.5V	0		3	dB
Operating Voltage Range	Vs		1.1		5.0	V
		f=1kHz, Pin=94dB			1	%
Distortion	THD	f=1kHz, Pin=115dB			5	%
		f=1kHz, Pin=120dB			10	%

3 Frequency Response Curve and Limits

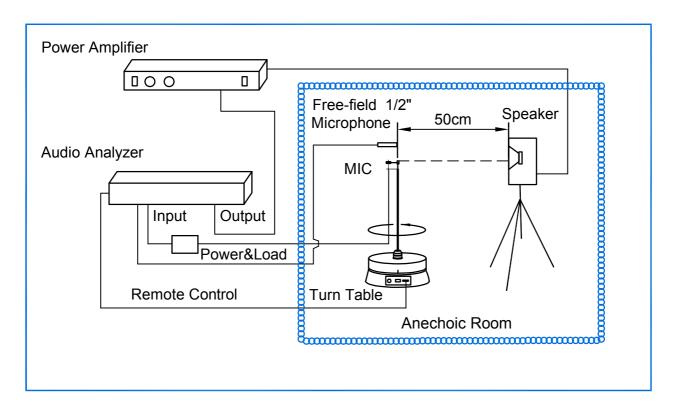




4 Measurement Circuit



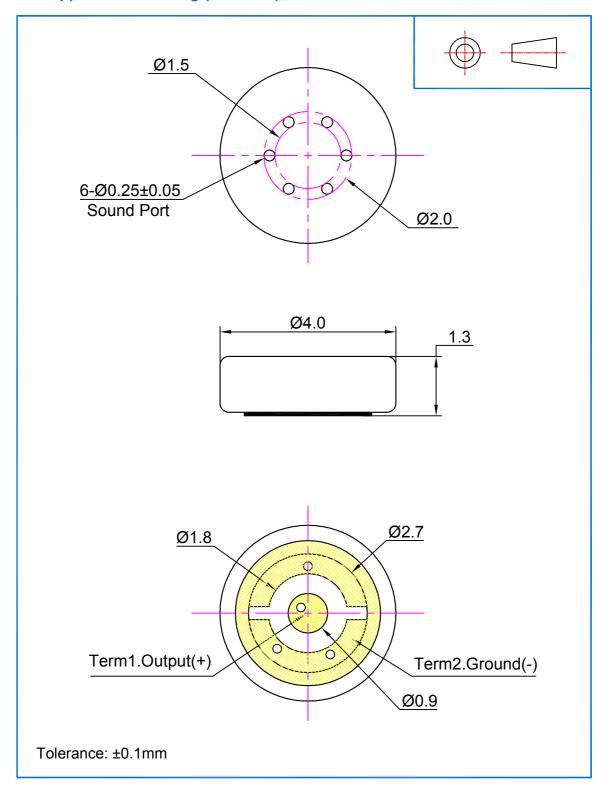
5 Test Setup Drawing





6 Mechanical Characteristics

6.1 Appearance Drawing (Unit: mm)

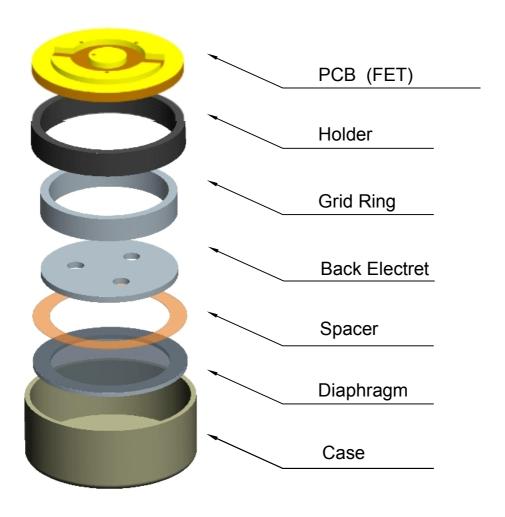


6.2 Weight

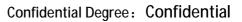
The weight of the MIC is less than 0.2g.



7 Structure of SMD MIC



No.	Item	Qty.	Vendor	Material
1	PCB	1	KJ	FR-4
2	Holder	1	Yuyuan	HTN
3	Grid Ring	1	Yuyuan	Brass with nickel-plated
4	Back Electret	1	Yinhe	Stainless steel with PTFE
5	Spacer	1	Wanda+GoerTek	PI
6	Diaphragm	1	GoerTek	Stainless ring +PPS with nickel-plated
7	Case	1	ABE	Brass with nickel-plated





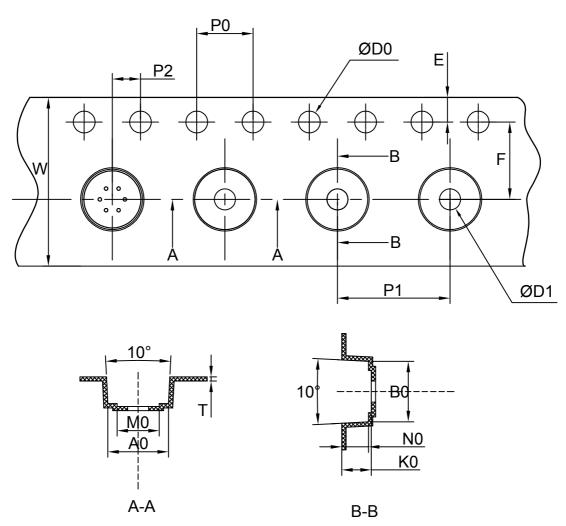
8 Reliability Test

o Reliabili	Reliability rest					
8.1 Vibration Test	To be no interference in operation after vibrations,10Hz to 55 Hz for 1 minute full amplitude 1.52mm,for 2 hours at three axises in state of standard packing,sensitivity to be within ± 3 dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 $^{\circ}$ C $^{\circ}$ +35 $^{\circ}$ C, R.H 25% $^{\circ}$ C75%)					
8.2 Drop Test	To be no interference in operation after dropped to steel plate each one time from 1.5 meter height ,12 times,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 $^{\circ}$ C $^{\circ}$ +35 $^{\circ}$ C, R.H 25% $^{\circ}$ 75%)					
8.3 Temperature Test	a) After exposure at +85°C for 200 hours, sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 °C ~+35°C, R.H 25% ~75%) b) After exposure at -40°C for 200 hours, sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 °C ~+35°C, R.H 25% ~75%)					
8.4 Humidity Test	After exposure at +60°C and 90~95% relative humidity for 200 hours,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 $^{\circ}$ C $^{\circ}$ +35 $^{\circ}$ C, R.H 25% $^{\circ}$ 75%)					
8.5 Temperature Cycle Test	After exposure at -40°C for 30 minutes, at 20°C for 10 minutes, at+85°c for 30 minutes, at 20°C for 10 minutes,5 cycles, sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 $^{\circ}$ C $^{\circ}$ +35 $^{\circ}$ C, R.H 25% $^{\circ}$ 75%)					
8.6 Temperature Shock Test	After exposure at -40 $^{\circ}$ C for 60 minutes, at+85 $^{\circ}$ C for 60 minutes(change time 20 seconds), 32 cycles,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 $^{\circ}$ C \sim +35 $^{\circ}$ C, R.H 25% \sim 75%)					
8.7 ESD Shock Test	The microphone under test must be discharged between each ESD exposure without ground. (contact:±8kV,air:±15kV) There is no interference in operation after 10 times exposure.					
8.8 Reflow Test	Adopt the reflow curve of item11.3,after two reflows,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 $^{\circ}$ C $^{\circ}$ +35 $^{\circ}$ C, R.H 25% $^{\circ}$ 75%)					



9 Package

9.1 Taping Specification



the dimensions as follows:

ITEM	W	E	F	ØD0	ØD1
DIM(mm)	12.0±0.30	1.75±0.10	5.50±0.05	1.50±0.10	1.55±0.10
ITEM	P0	10P0	P1	A0	В0
DIM(mm)	4.00±0.10	40.00±0.20	8.00±0.10	4.20±0.05	4.20±0.05
ITEM	K0	P2	Т	MO	N0
DIM(mm)	1.70±0.10	2.00±0.05	0.35±0.05	3.00±0.05	1.50±0.1

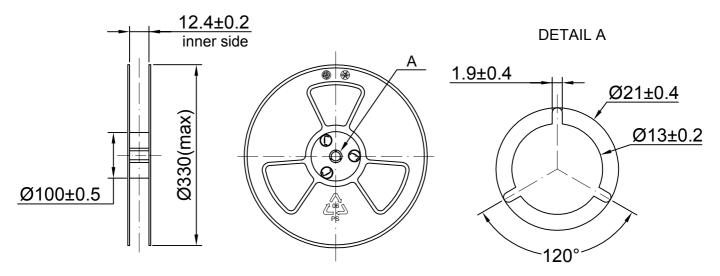


9.2 Reel Dimension

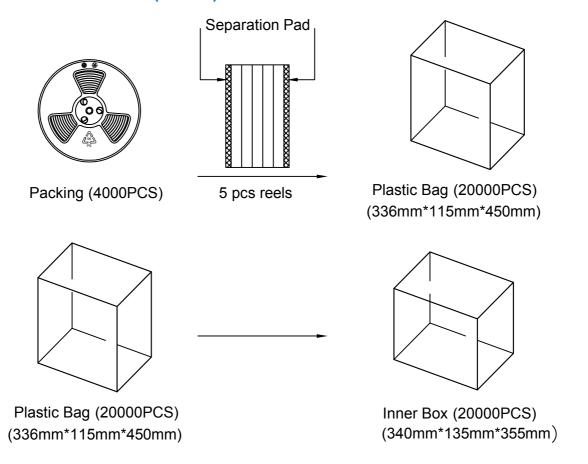
7 " reel for sample stage

13 " reel will be provided for the mass production stage

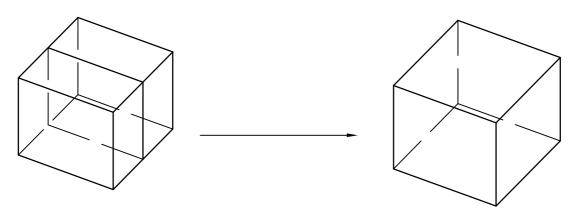
The following is 13" reel dimensions (unit:mm)



9.3 The content of box(13" reel)



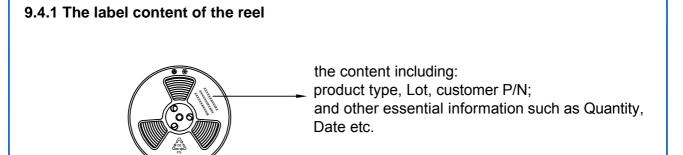




Two Inner Box(40000PCS)

Outer Box(40000PCS) (370mm*300mm*390mm)

9.4 Packing Explain





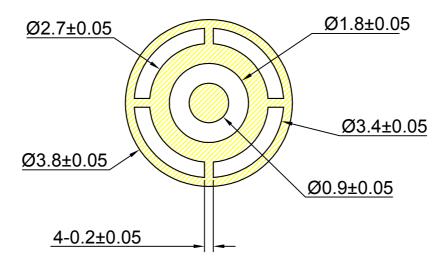
10 Stock and Transportation

- 10.1 Keep ECM in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field.
- 10.2 The ECM with normal pack can be transported by ordinary conveyances. Please protect products against moist, shock, sunburn and pressure during transportation.
- 10.3 Storage Temperature Range: -40 °C~+85 °C
- 10.4 Operating Temperature Range: -30°C~+70°C

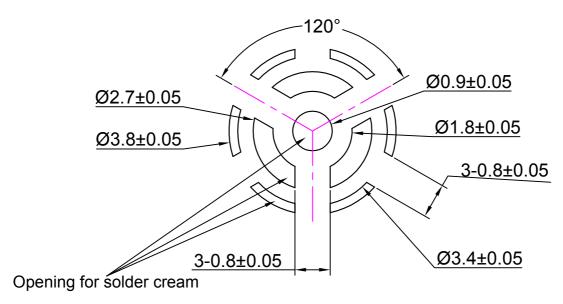


11 Land Pattern Recommendation (Unit: mm)

11.1 Soldering Surface - Land Pattern



11.2 Metal Mask Pattern



- thickness of metal mask:0.1mm

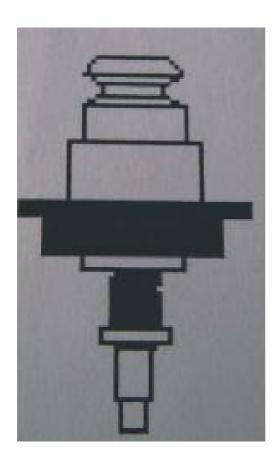


12 Recommend Soldering

12.1 Soldering Machine Condition

Temperature control	8 zones		
Heater Type	Hot Air		
Solder Type	Lead-free		

12.2 The pattern of the nozzle

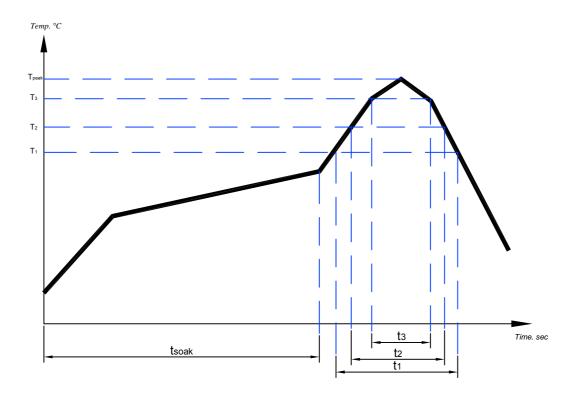


dimension of nozzle:504 external diameter: 1.5mm; inside diameter: 1.0mm;

Pick up position:bottom border of microphone



12.3 Reflow Profile



Pb-free reflow profile requirements for soldering heat resistance

Parameter	Reference	Specification
Average Temperature Gradient in Preheating		2.5℃/s
Soak Time	t _{soak}	2-3 Minutes
Time Above 217 ℃	t ₁	Max 60s
Time Above 230 ℃	t ₂	Max 50s
Time Above 250 ℃	t ₃	Max 10s
Peak Temperature In Reflow	T _{peak}	255°C (-0/+5°C)
Temperature Gradient In Cooling		Max -5°C/s

When SMD MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.



13 Cautions when using SMD MIC

13.1 X-ray inspection

The microphone should not be subjected to X-ray inspection. If it is absolutely necessary to do inspection using X-ray, the setting conditions with the following conditions:

Distance: >0.08meter; Current: <0.080mA; Time: <30s; Voltage: <80kV.

13.2 Board wash restrictions

It is very important not to wash the PCBA after reflow process, or this could damage the microphone.

13.3 Nozzle restrictions

It is very important not to pull a nozzle over the post hole of the microphone. or this could damage the microphone.

13.4 Others restrictions

The pressure on the MIC shouldn't be more than 10N; The connecting between the institution and MIC should use rubber or Poron.

14 Output Inspection standard

output inspection standard is excuted according to <<ISO2859-1:1999>>.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Microphones category:

Click to view products by Goertek manufacturer:

Other Similar products are found below:

BCM4013OLFC-42-JST-ZHR-2 FG-23329-P142 FB-EI-31809-000 SPM04C-38/1186-T/R BCM4013OSBC-42 LF TOW-1242P-R
BCM9745-44 BCM9765 BCM9767P LD-MC-0905P LD-MC-6035 LD-MC-9765 CMC-4015-40P PMO-6022SN-42UQ PMOF-6027WN44KDQ PMO-4015PN-42KDQ CMC-6027-42L100 PMO-6027P-40KDQ PMOF-6050S-44UQ PMO-4530PN-47UQ PMO-4015MN-42HXQ
CMC-6036-40T CMC-9745-44P PMOF-9767NP-46DQ PMOF-9745W-42UQ PMOF-9745P-39UQ CMC-6015-42P CMC-4015-40T PMO6022PN-48KDQ PMOF-9745S-42UQ PMOF-9767NS-40DQ PMOF-6027NSN-36KDQ AOM-5024L-HD-R ROM-2235P-HD-R 1007089-1
CMC-9745-130T BJ-28471-000 TOM-1537L-HD-R ROM-2235L-HD-R DUM-4546L-C3310-R CMC-4015-130T CMC-6050-40T CMC6035-130T CMC-6015-47P BCM9767-42 LD-MC-4011 LD-MC-6027 LD-MC-6035P LD-MC-6035W LD-MC-9765P